

8327GL5



Non-Silicone Liquid Thermal Gel

8327GL5 is a 1-part, silicone-free, high temperature, soft gel offering very high thermal conductivity and flame retardancy. This form-in-place, non-curable gel is easy to dispense and conforms to the component/heatsink interface, ensuring all air is displaced and eliminating hotspots. Since the gel does not cure, circuits can be powered up immediately following application, offering exceptional convenience.

It is most often used as a gap filler on heatsinks to CPUs, LEDs, and other electronic components. Its high thermal conductivity makes it ideal for energy-intensive devices like telecommunications equipment, PCs for gamers and electric vehicle battery packs.



Features & Benefits

- Very high thermal conductivity
- Flame retardant—meets UL94 V-0
- High temperature stability
- 1-part, non-curable, dispensable gel
- Zero pump out—no slump under low pressure
- Silicone-free, will not contaminate surfaces
- Low modulus, ideal for aggressive thermal cycling conditions

Available Packaging

Cat. No.	Packaging	Net Vol.	Net Wt.
8327GL5-30ML	Cartridge	28.7 mL	66 g
8327GL5-180ML	Cartridge	127 mL	294 g

Contact Information

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Properties

Color	Grey
Resistivity	$10^9 \Omega \cdot \text{cm}$
Dissipation Factor @ 1 kHz	0.005
Breakdown Voltage @ 1 mm	3 200 V
Thermal Conductivity @ 25 °C	5.1 W/(m·K)
Service Temperature Range	-55–150 °C
Intermittent Temperature	180 °C
Density	2.3 g/mL
Viscosity @ 25 °C	3 500–5 000 Pa·s

Storage and Handling

Store between 16 and 27 °C in a dry area, away from sunlight (see SDS).

Disclaimer

This information is believed to be accurate. It is intended for professional end-users who have the skills required to evaluate and use the data properly. M.G. Chemicals Ltd. does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.